

# *ECE680: Physical VLSI Design*

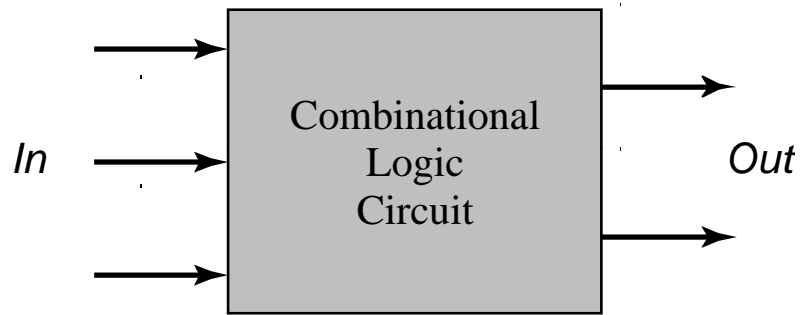
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## Chapter III

### CMOS Device, Inverter, Combinational circuit Logic and Layout

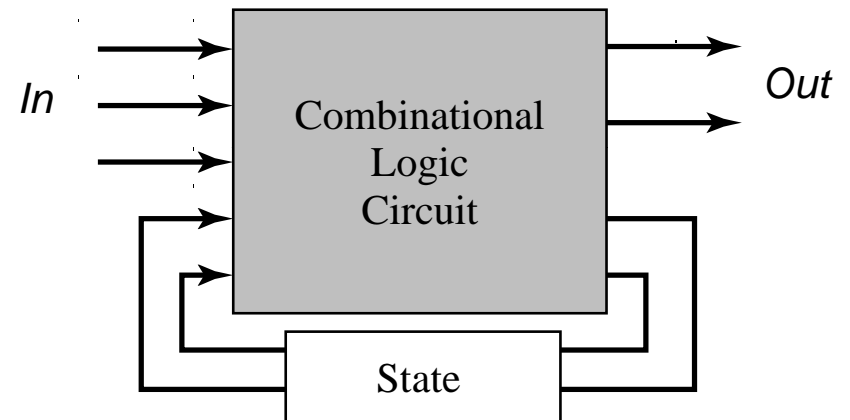
### Part 3 Combinational Logic Gates (textbook chapter 6)

# Combinational vs. Sequential Logic



Combinational

$$\text{Output} = f(\text{In})$$



Sequential

$$\text{Output} = f(\text{In}, \text{Previous In})$$

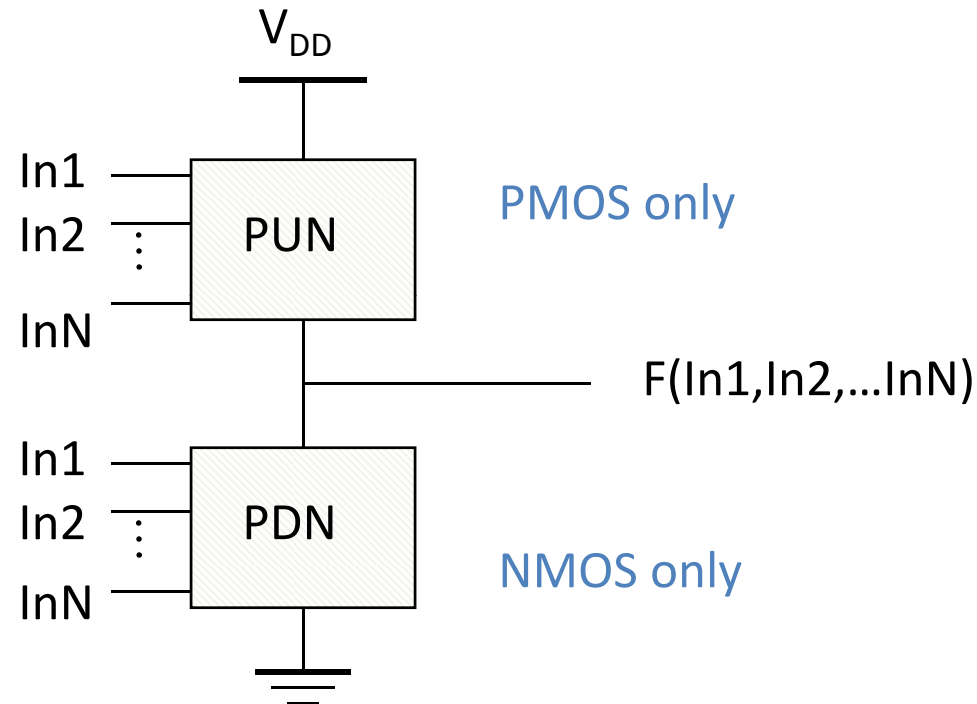
# Static CMOS Circuit

At every point in time (except during the switching transients) each **gate output is connected to either  $V_{DD}$  or  $V_{SS}$  via a low-resistive path.**

The outputs of the gates **assume at all times the value of the Boolean function**, implemented by the circuit (ignoring, once again, the transient effects during switching periods).

This is in contrast to the **dynamic** circuit class, which relies on temporary storage of signal values on the capacitance of high impedance circuit nodes.

# Static Complementary CMOS

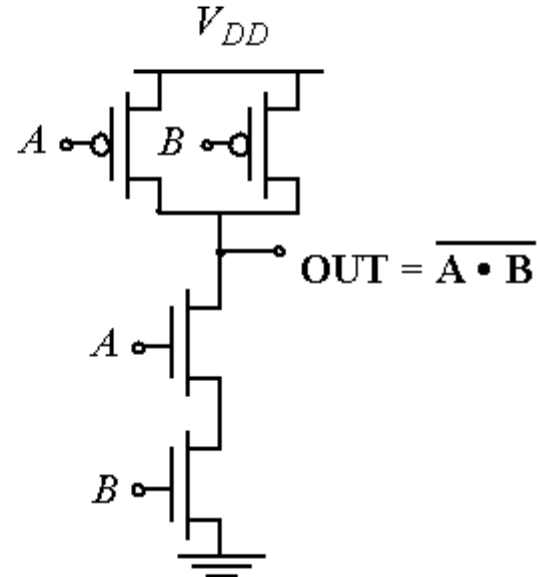


PUN and PDN are dual logic networks

# Example Gate: NAND

A	B	Out
0	0	1
0	1	1
1	0	1
1	1	0

Truth Table of a 2 input NAND gate



PDN:  $G = A B \Rightarrow$  Conduction to GND

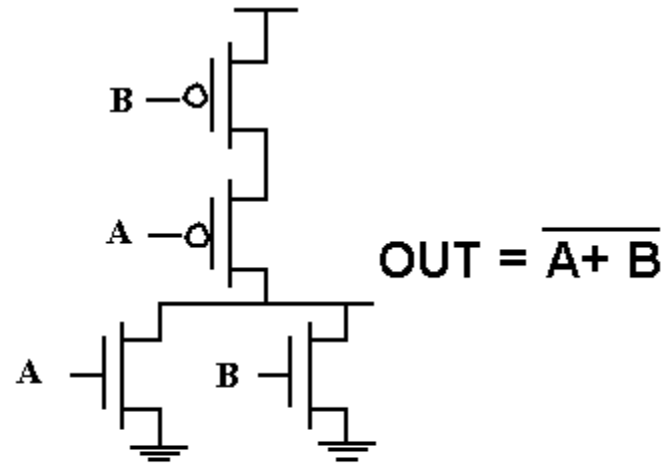
PUN:  $F = \overline{A} + \overline{B} = \overline{AB} \Rightarrow$  Conduction to  $V_{DD}$

$$\overline{G(In_1, In_2, In_3, \dots)} \equiv F(\overline{In_1}, \overline{In_2}, \overline{In_3}, \dots)$$

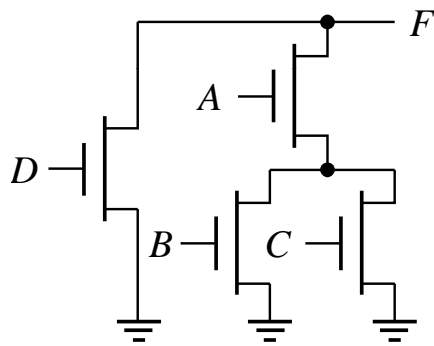
# Example Gate: NOR

A	B	Out
0	0	1
0	1	0
1	0	0
1	1	0

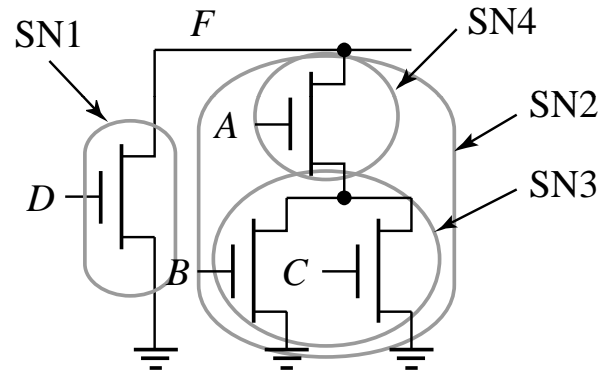
Truth Table of a 2 input NOR gate



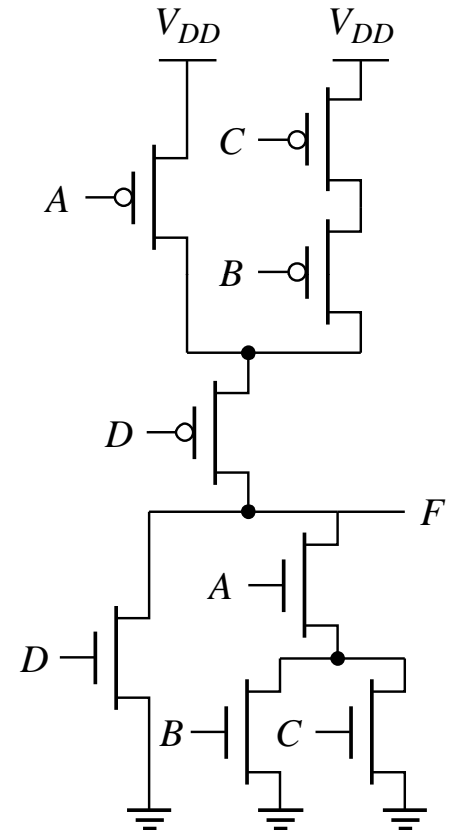
# Constructing a Complex Gate



(a) pull-down network



(b) Deriving the pull-up network hierarchically by identifying sub-nets



(c) complete gate

# Properties of Complementary CMOS Gates

**High noise margins:**

$V_{OH}$  and  $V_{OL}$  are at  $V_{DD}$  and GND, respectively.

**No static power consumption**

There never exists a direct path between  $V_{DD}$  and  $V_{SS}$  (GND) in steady-state mode.

**Comparable rise and fall times:**

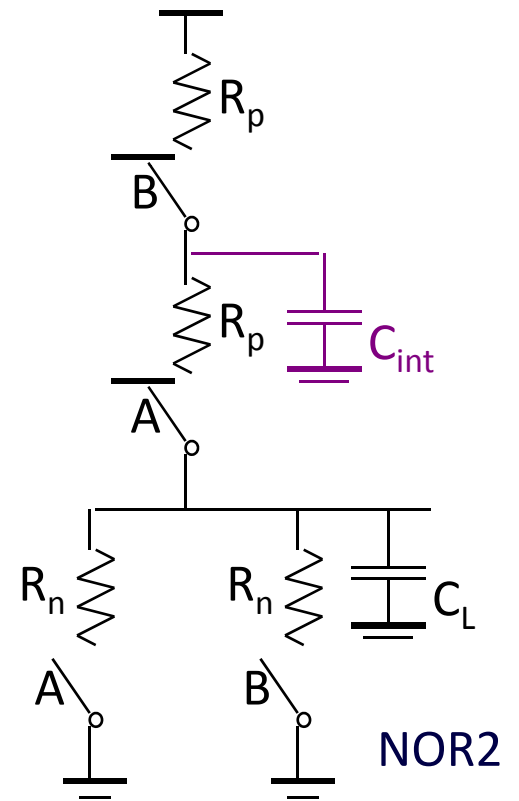
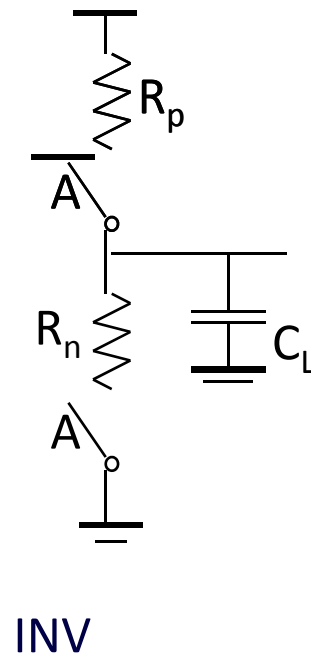
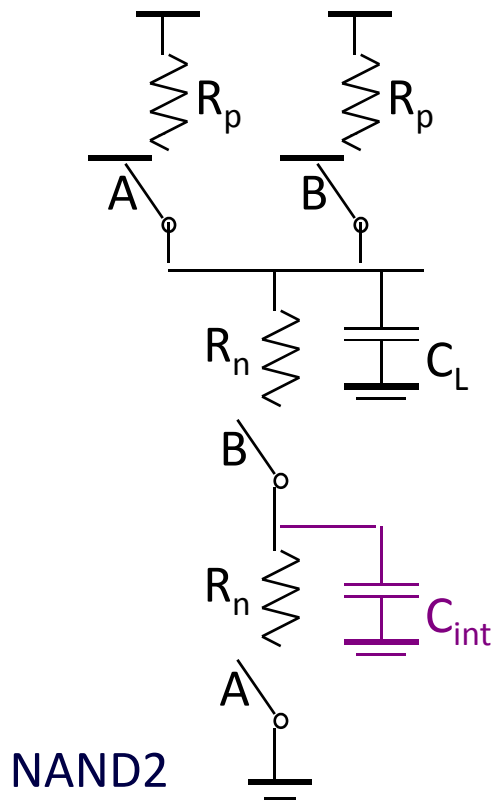
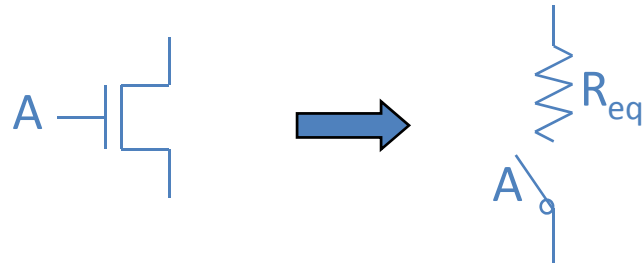
(under appropriate sizing conditions)



# CMOS Properties

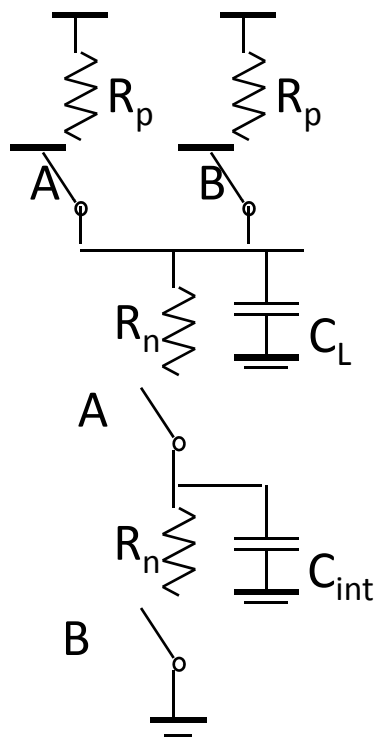
- Full rail-to-rail swing; **high noise margins**
- Logic levels not dependent upon the relative device sizes; **ratioless**
- Always a path to Vdd or Gnd in steady state; **low output impedance**
- Extremely **high input resistance**; nearly zero steady-state input current
- No direct path steady state between power and ground; **no static power dissipation**
- Propagation delay function of load capacitance and resistance of transistors

# Switch Delay Model



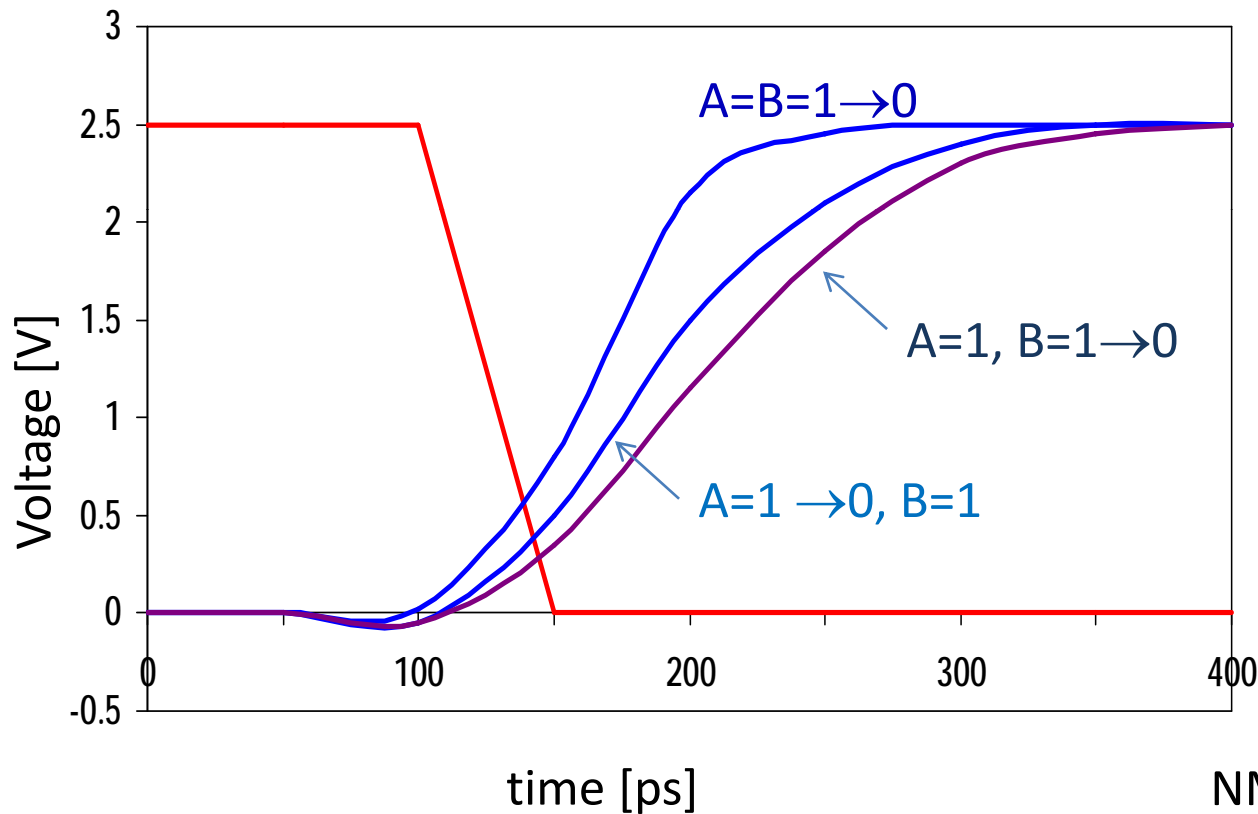
# Input Pattern Effects on Delay

(consider a NAND gate with A and B input)



- Delay is dependent on the **pattern** of inputs
- Low to high transition
  - both inputs go low
    - delay is  $0.69 R_p/2 C_L$
  - one input goes low
    - delay is  $0.69 R_p C_L$
- High to low transition
  - both inputs go high
    - delay is  $0.69 2R_n C_L$

# Delay Dependence on Input Patterns

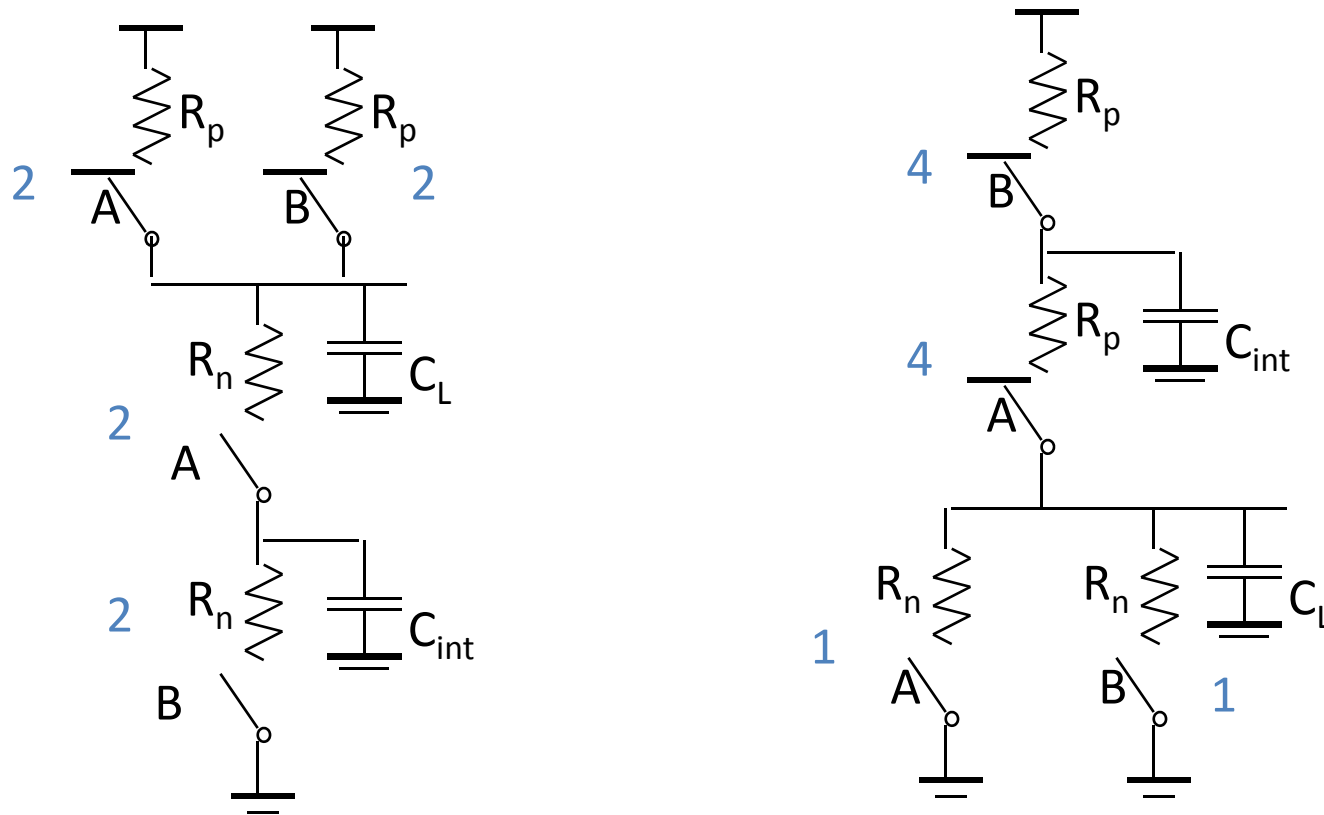


Input Data Pattern	Delay (psec)
A=B=0→1	69
A=1, B=0→1	62
A= 0→1, B=1	50
A=B=1→0	35
A=1, B=1→0	76
A= 1→0, B=1	57

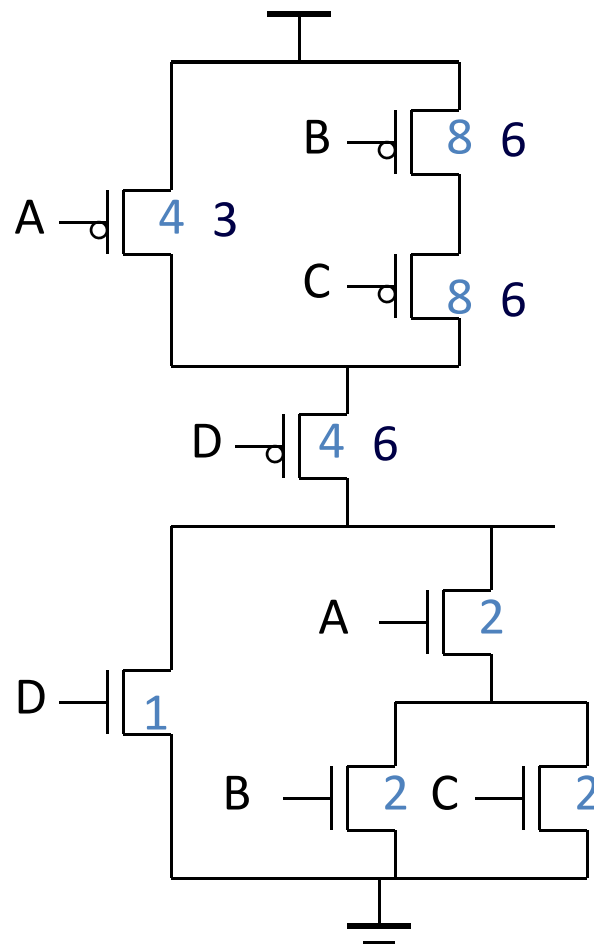
NMOS =  $0.5\mu\text{m}/0.25\mu\text{m}$   
 PMOS =  $0.75\mu\text{m}/0.25\mu\text{m}$   
 $C_L = 100\text{ fF}$

# Transistor Sizing

(assume inverter  $W_p/W_n = 2$ )

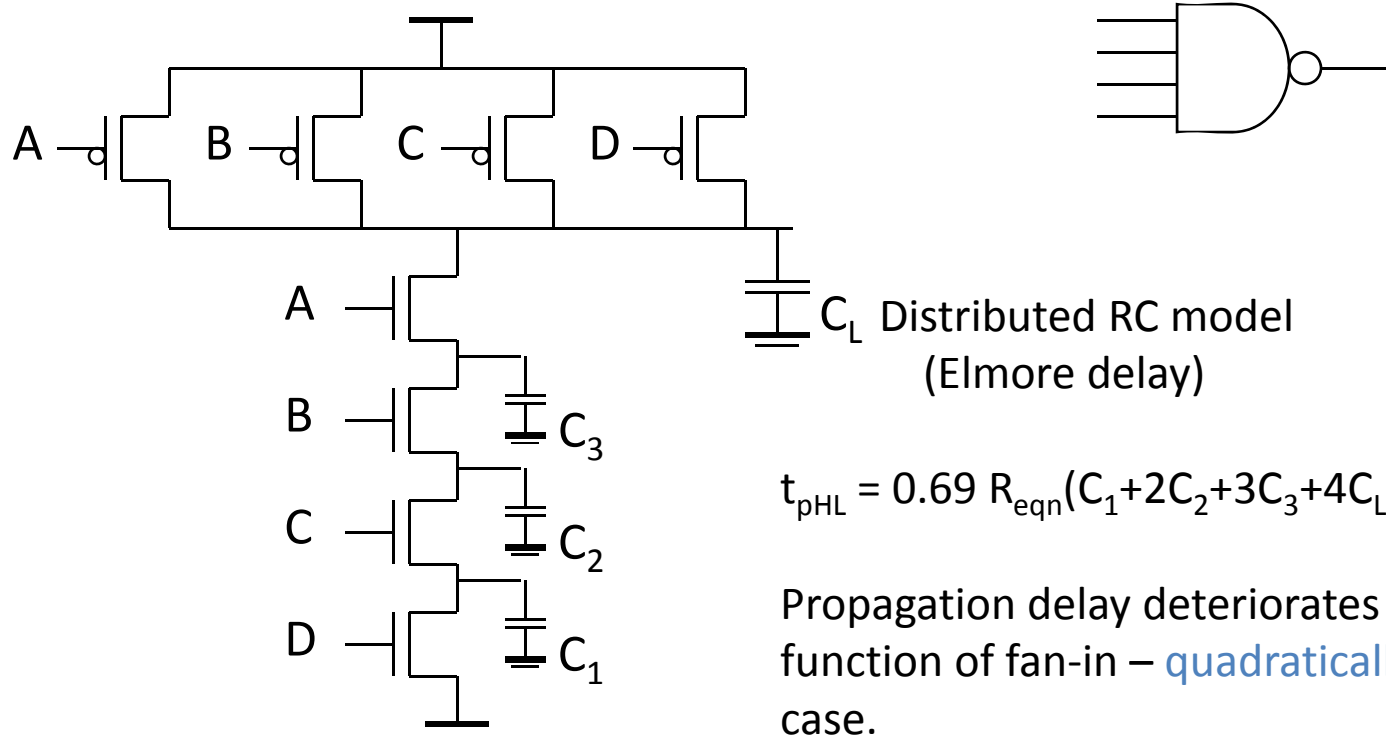


# Transistor Sizing a Complex CMOS Gate



$$\text{OUT} = D + A \cdot (B + C)$$

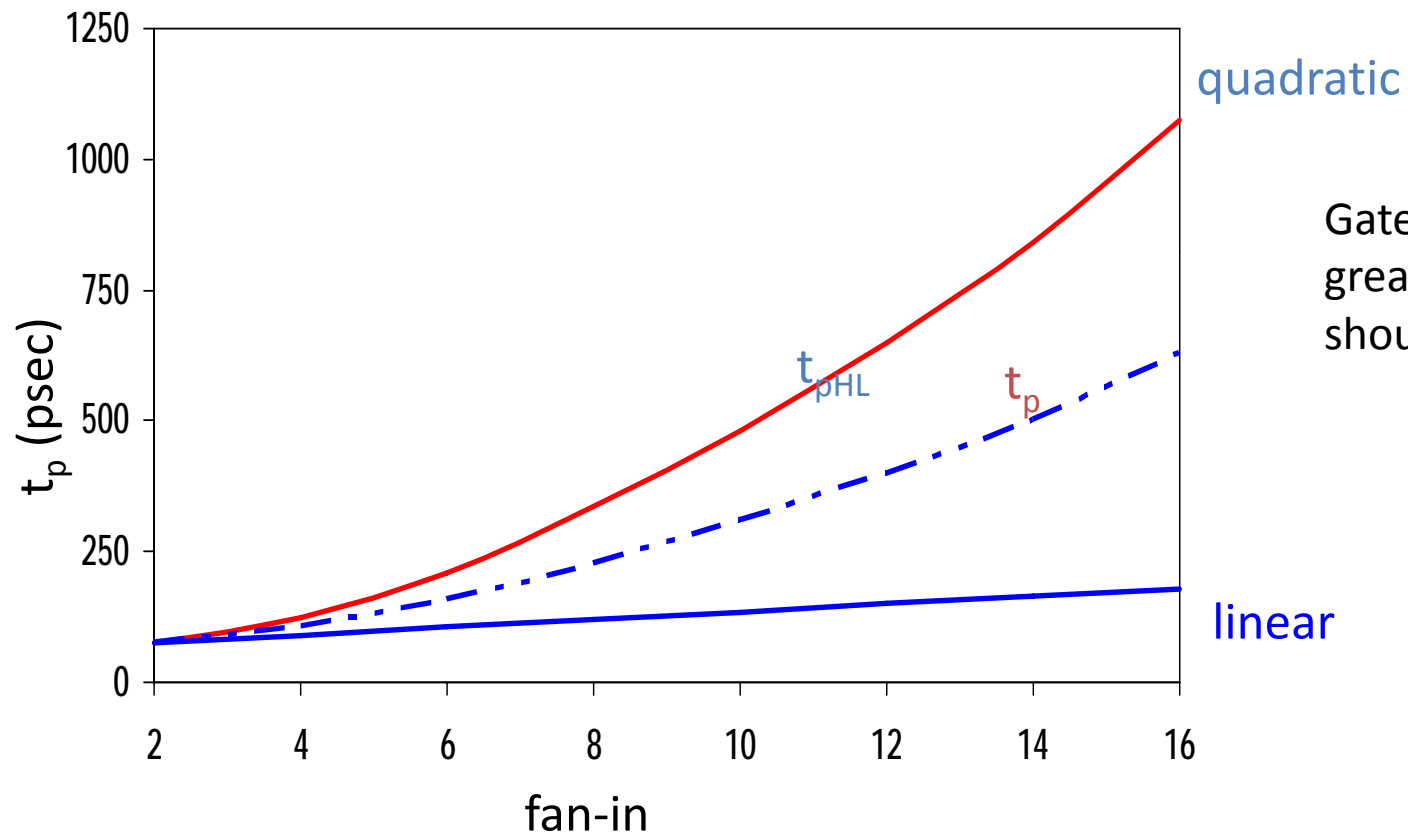
# Fan-In Considerations



$$t_{pHL} = 0.69 R_{eqn} (C_1 + 2C_2 + 3C_3 + 4C_L)$$

Propagation delay deteriorates rapidly as a function of fan-in – **quadratically** in the worst case.

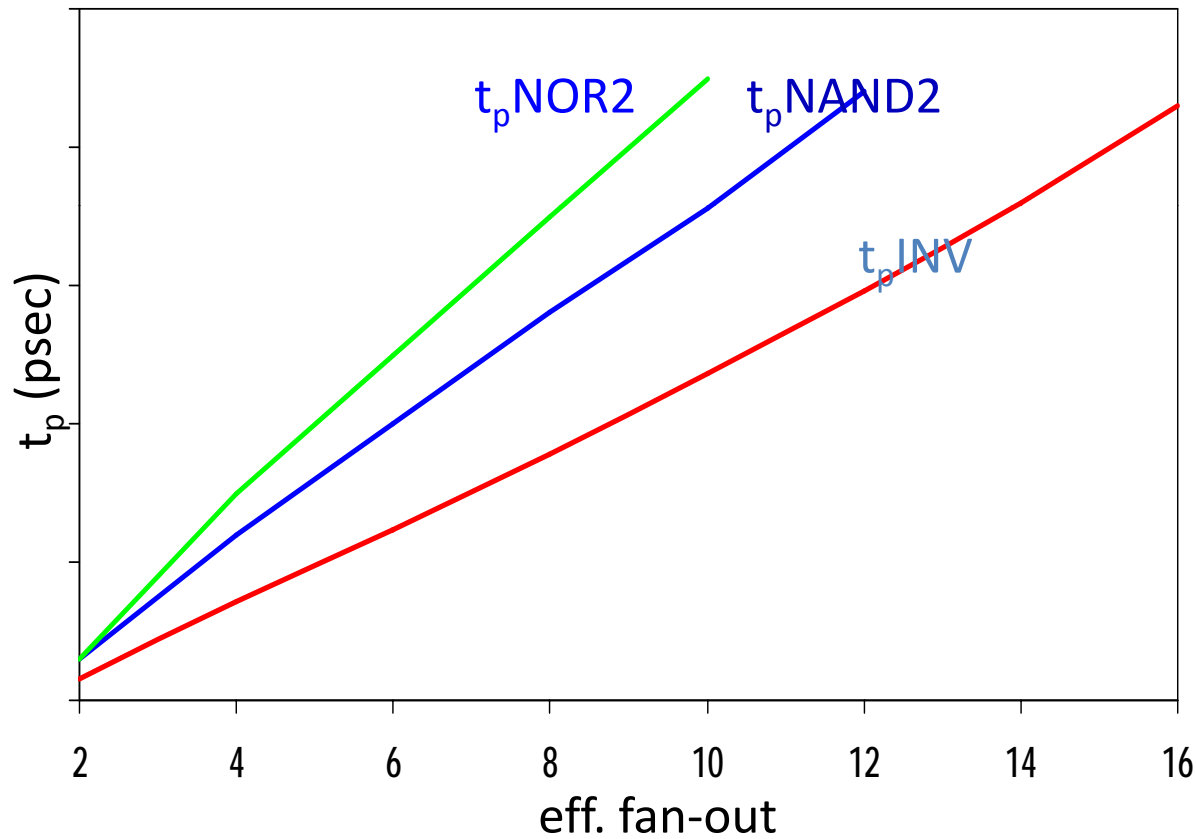
# $t_p$ as a Function of Fan-In



Gates with a fan-in greater than 4 should be avoided.



# $t_p$ as a Function of Fan-Out



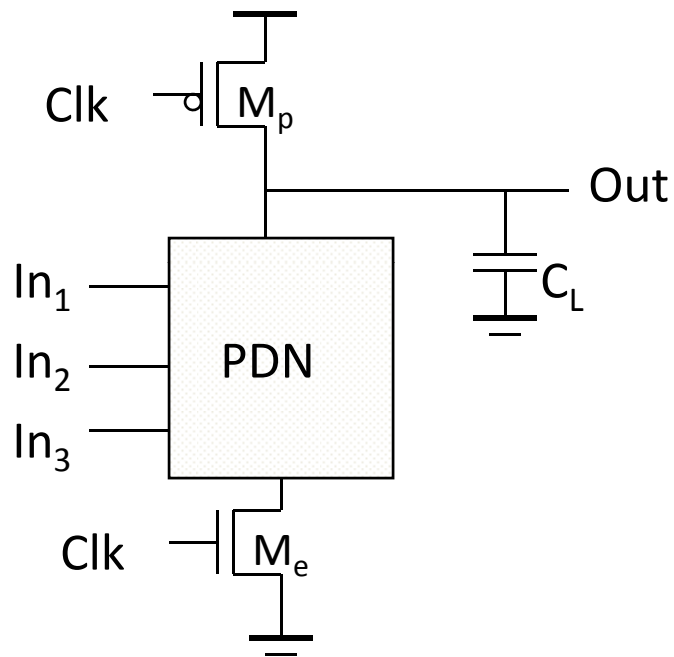
All gates have the same drive current.

Slope is a function of “driving strength”

# Dynamic CMOS

- In **static** circuits at every point in time (except when switching) the output is connected to either GND or  $V_{DD}$  via a low resistance path.
  - fan-in of  $n$  requires  $2n$  ( $n$  N-type +  $n$  P-type) devices
- **Dynamic** circuits rely on the temporary storage of signal values on the capacitance of high impedance nodes.
  - requires on  $n + 2$  ( $n+1$  N-type + 1 P-type) transistors

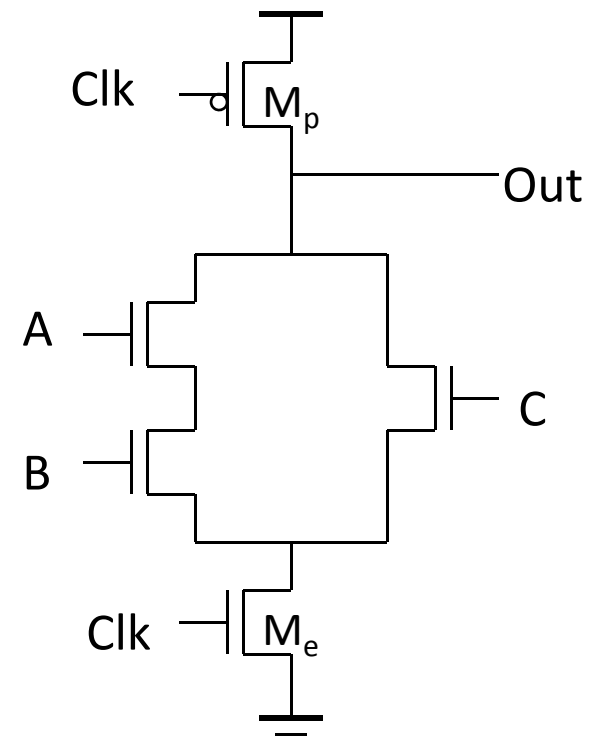
# Dynamic Gate



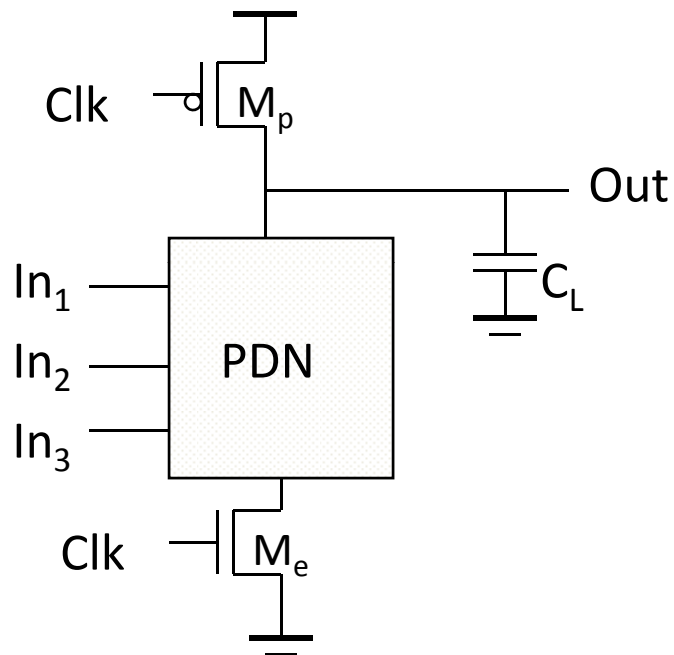
Two phase operation

Precharge (CLK = 0)

Evaluate (CLK = 1)



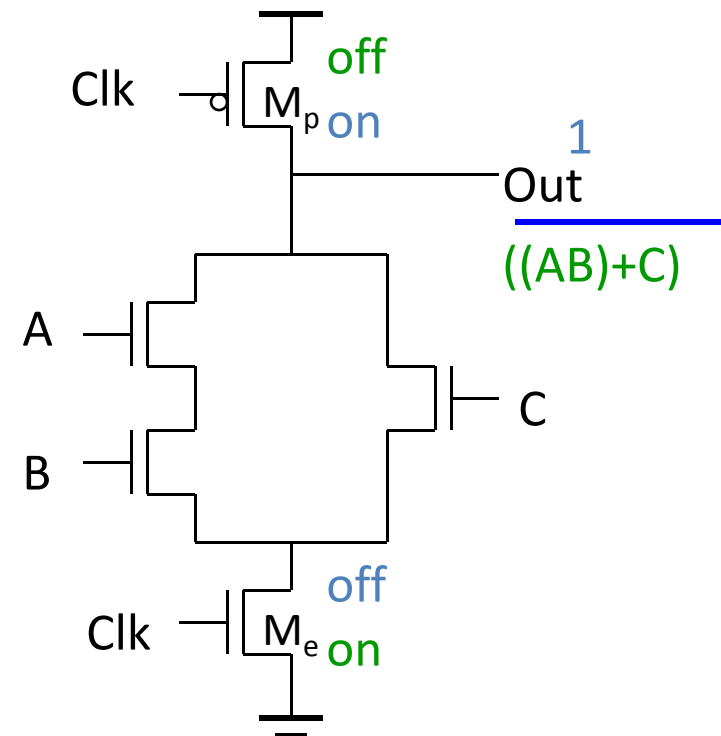
# Dynamic Gate



Two phase operation

Precharge ( $Clk = 0$ )

Evaluate ( $Clk = 1$ )



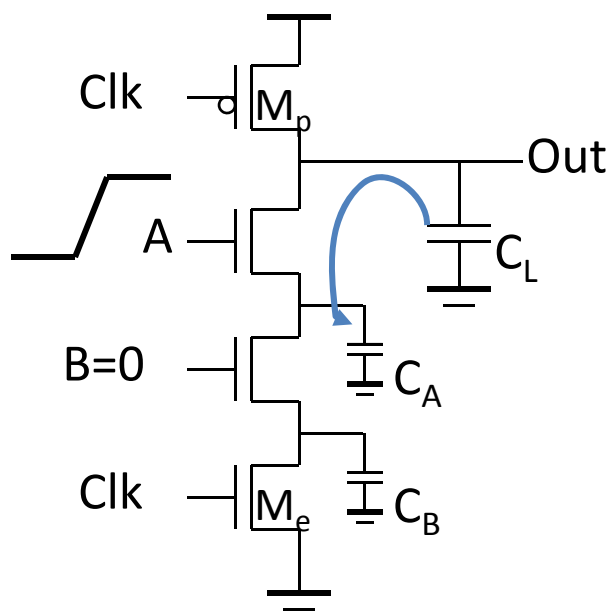
# Properties of Dynamic Gates

- Logic function is implemented by the PDN only
  - number of transistors is  $N + 2$  (versus  $2N$  for static complementary CMOS)
- Full swing outputs ( $V_{OL} = \text{GND}$  and  $V_{OH} = V_{DD}$ )
- Non-ratioed - sizing of the devices does not affect the logic levels
- Faster switching speeds
  - reduced load capacitance due to **lower input** capacitance ( $C_{in}$ )
  - reduced load capacitance due to smaller output loading ( $C_{out}$ )
  - no  $I_{sc}$ , so all the current provided by PDN goes into discharging  $C_L$

# Properties of Dynamic Gates

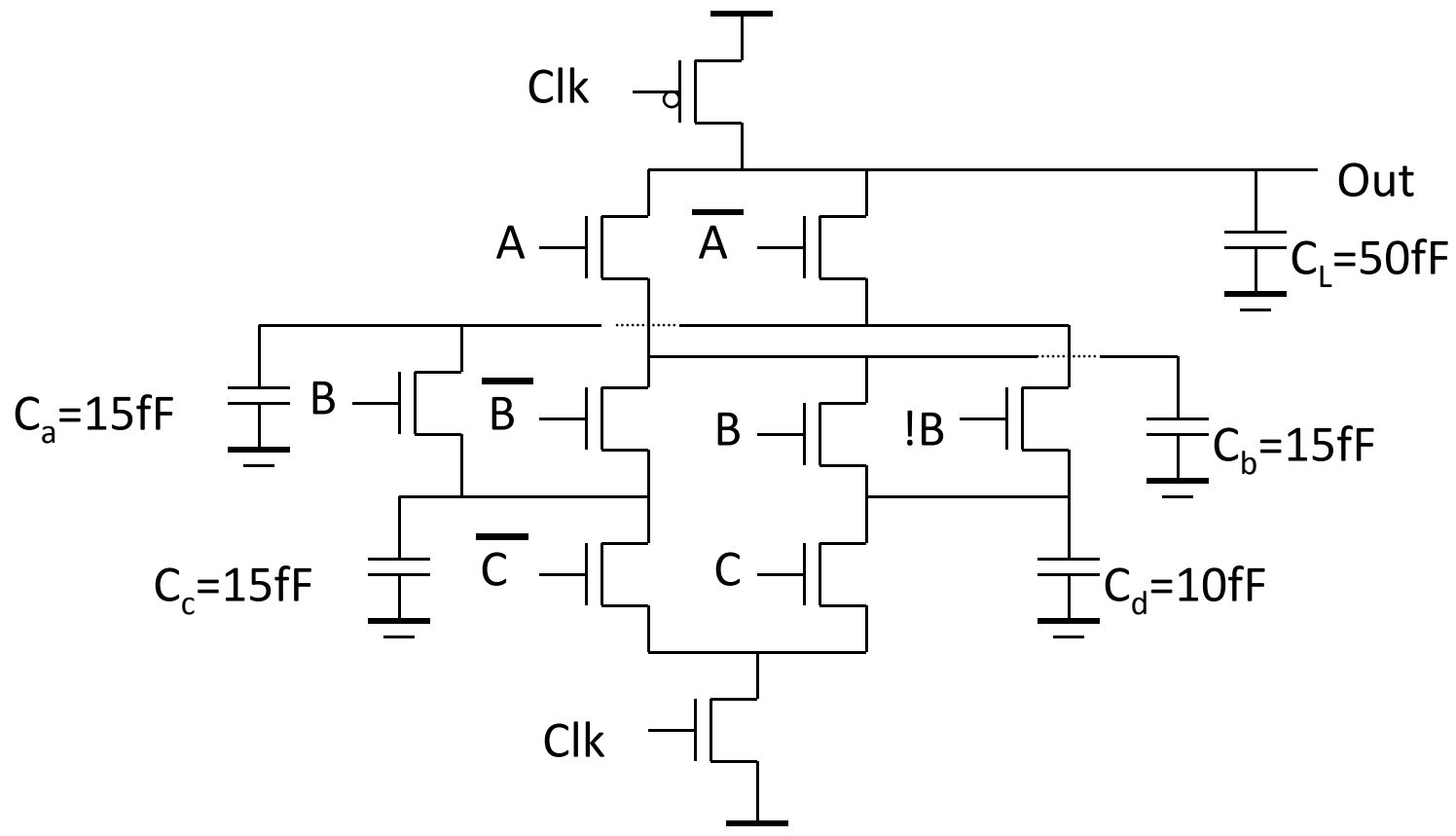
- Overall power dissipation usually **higher** than static CMOS
  - no static current path ever exists between  $V_{DD}$  and GND (including  $P_{sc}$ )
  - no glitching
  - **higher transition probabilities**
  - **extra load on Clk**
- PDN starts to work as soon as the input signals exceed  $V_{Tn}$ , so  $V_M$ ,  $V_{IH}$  and  $V_{IL}$  equal to  $V_{Tn}$ 
  - low noise margin ( $NM_L$ )
- Needs a precharge/evaluate clock

# Issues in Dynamic Design 2: Charge Sharing



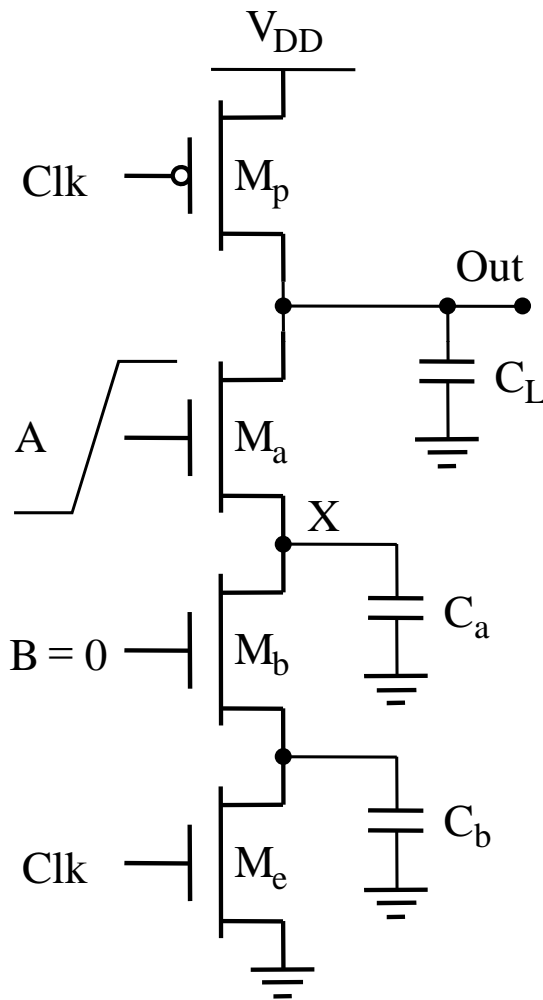
Charge stored originally on  $C_L$  is redistributed (shared) over  $C_L$  and  $C_A$  leading to reduced robustness

# Charge Sharing Example





# Charge Sharing



**case 1) if  $\Delta V_{out} < V_{Tn}$**

$$C_L V_{DD} = C_L V_{out}(t) + C_a (V_{DD} - V_{Tn}(V_X))$$

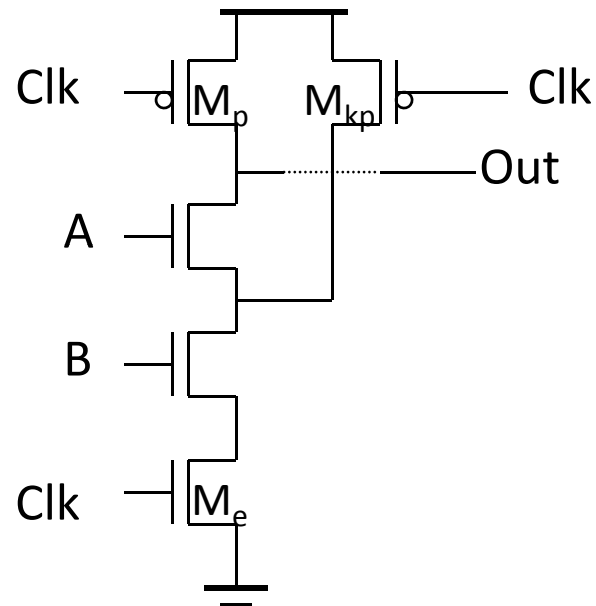
or

$$\Delta V_{out} = V_{out}(t) - V_{DD} = -\frac{C_a}{C_L} (V_{DD} - V_{Tn}(V_X))$$

**case 2) if  $\Delta V_{out} > V_{Tn}$**

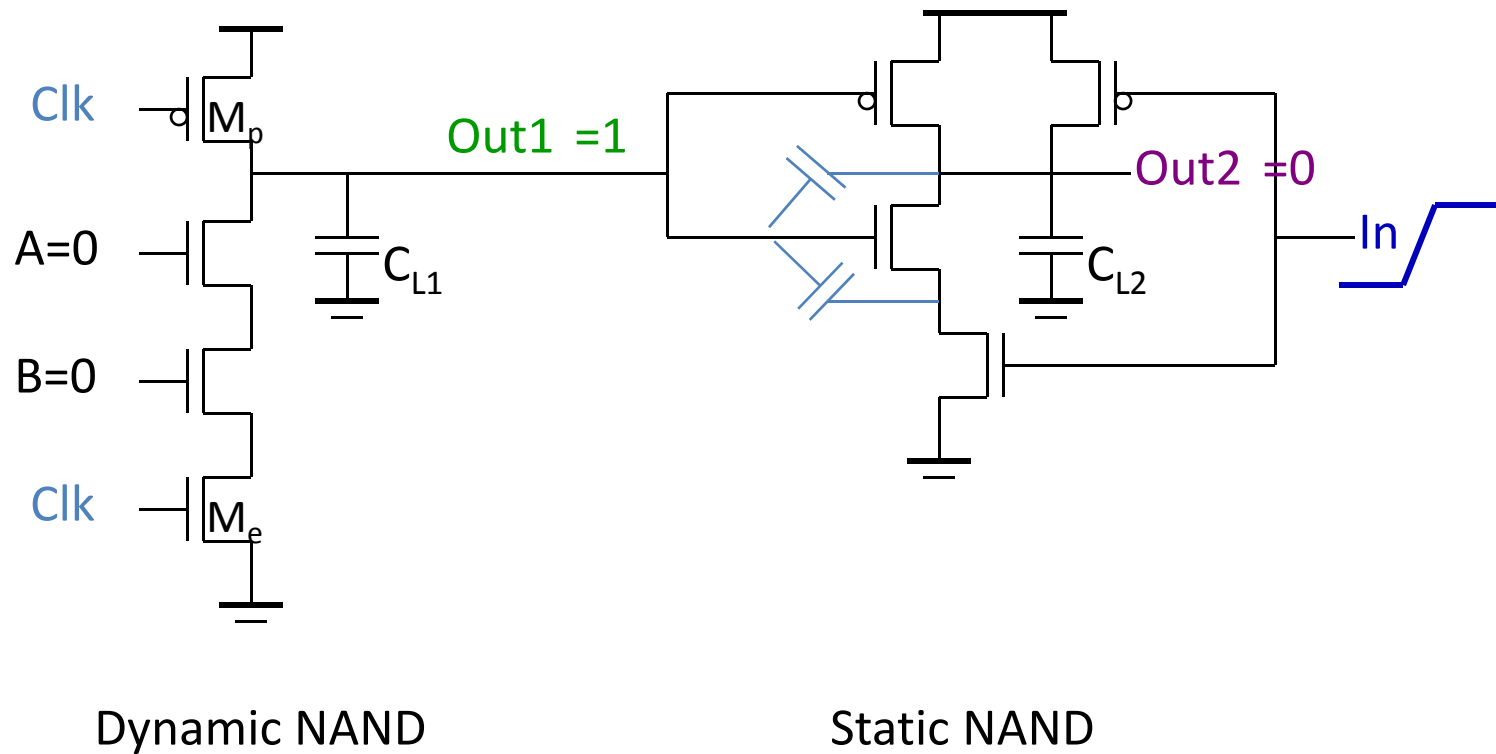
$$\Delta V_{out} = -V_{DD} \left( \frac{C_a}{C_a + C_L} \right)$$

# Solution to Charge Redistribution

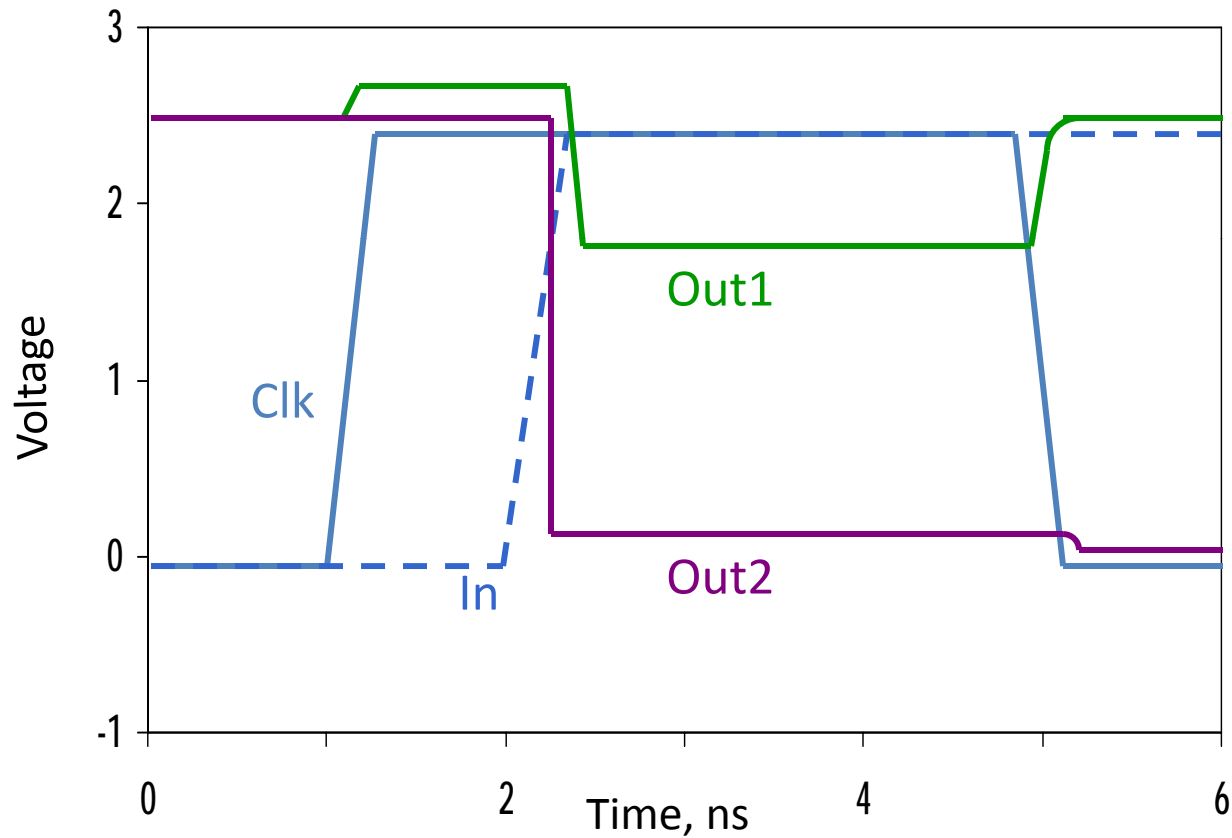


Precharge internal nodes using a clock-driven transistor (at the cost of increased area and power)

# Issues in Dynamic Design 3: Backgate Coupling

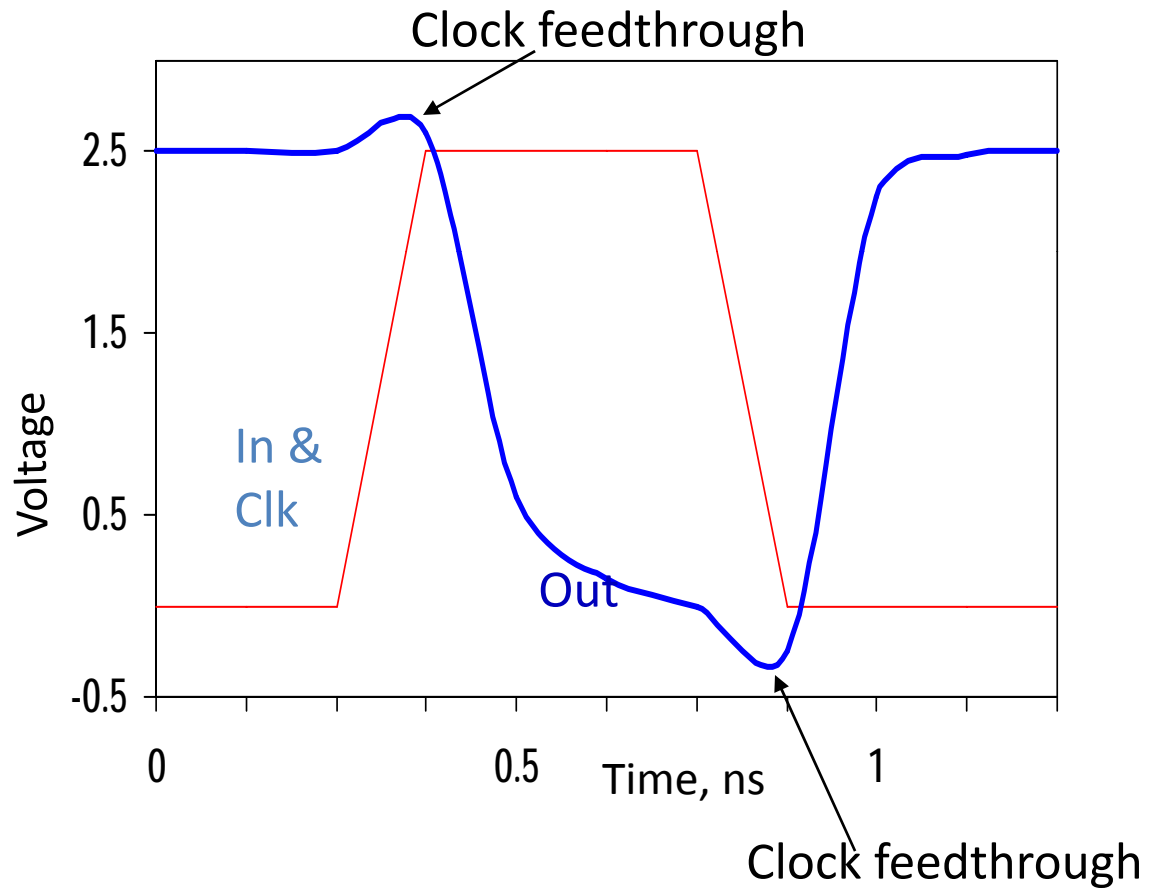
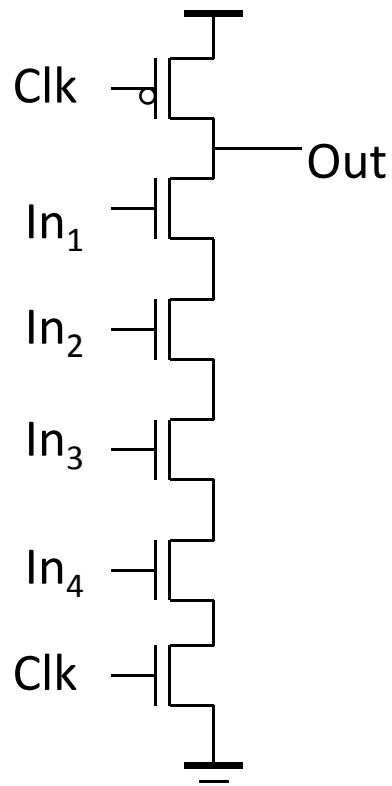


# Backgate Coupling Effect





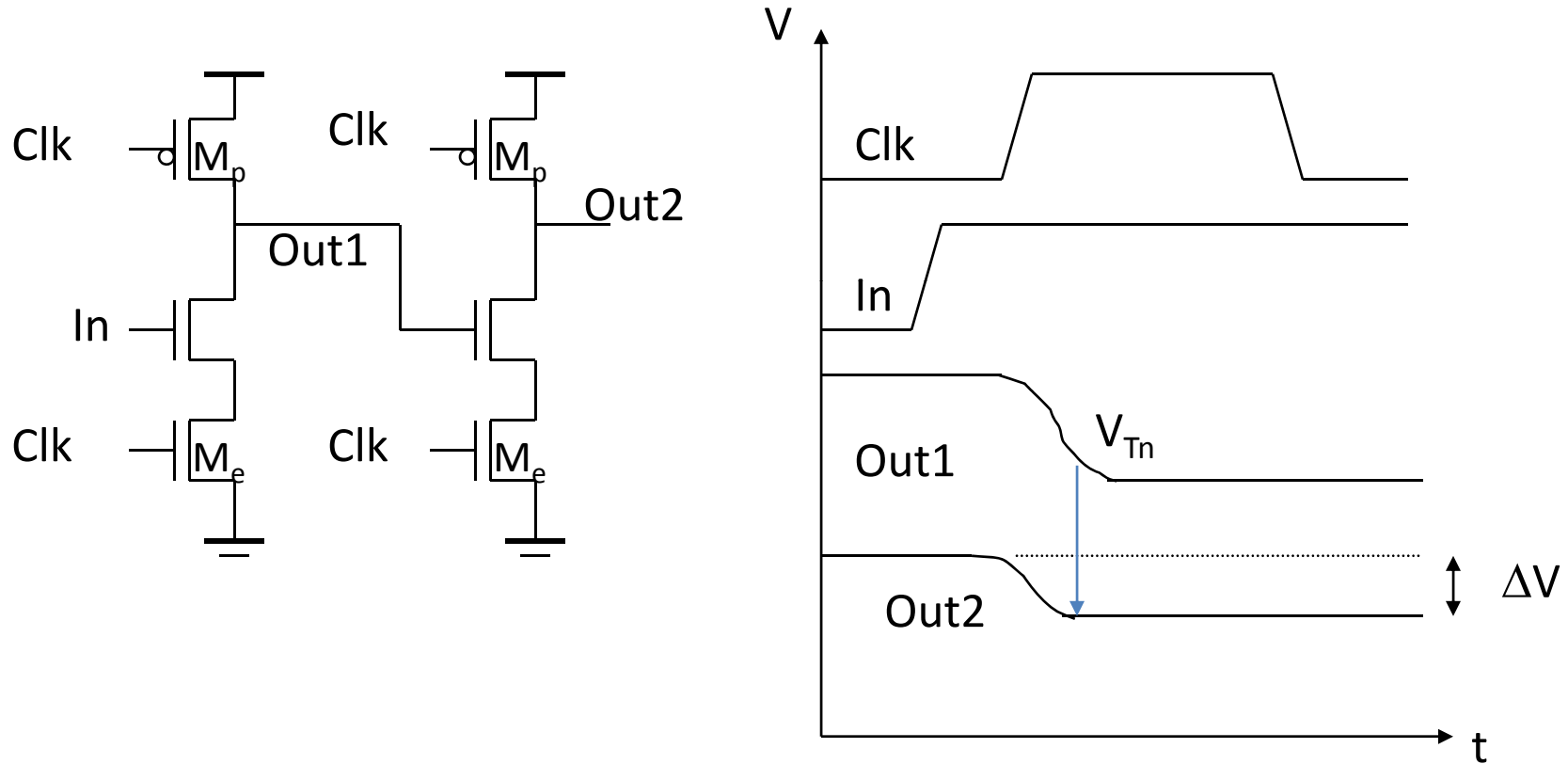
# Clock Feedthrough



# Other Effects

- Capacitive coupling
- Substrate coupling
- Minority charge injection
- Supply noise (ground bounce)

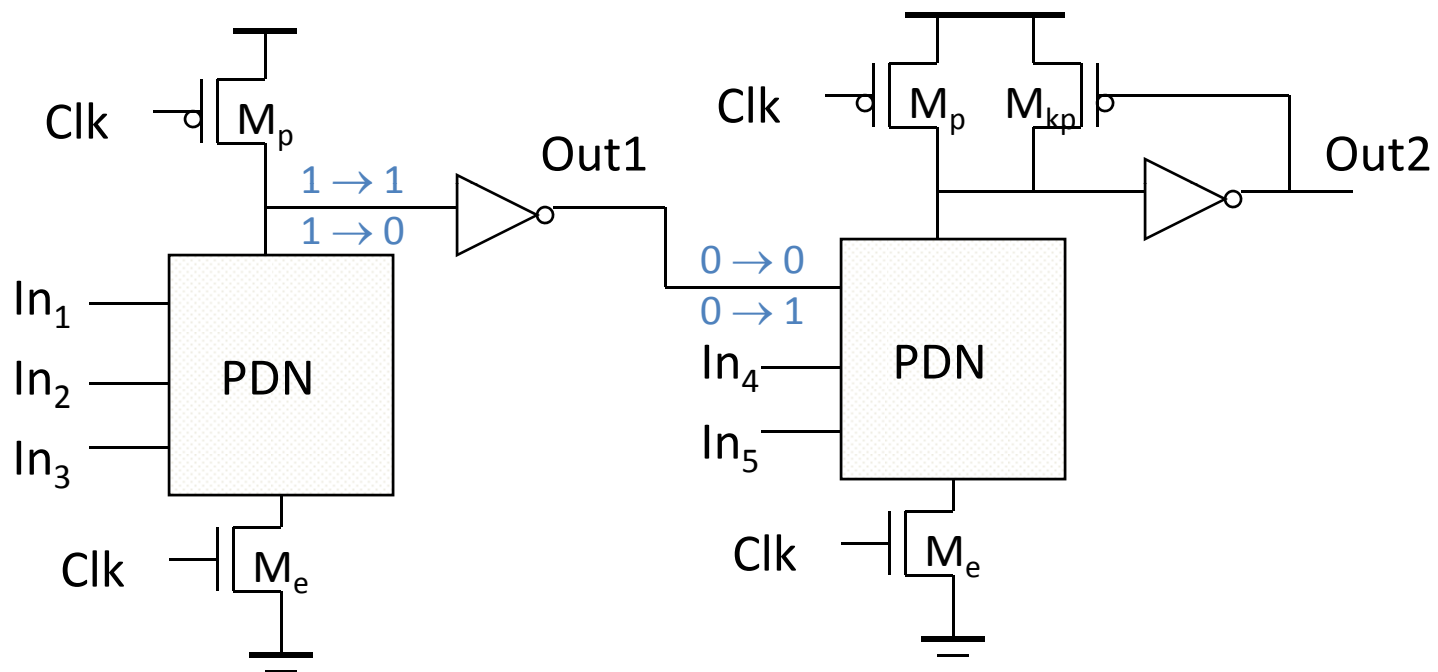
# Cascading Dynamic Gates



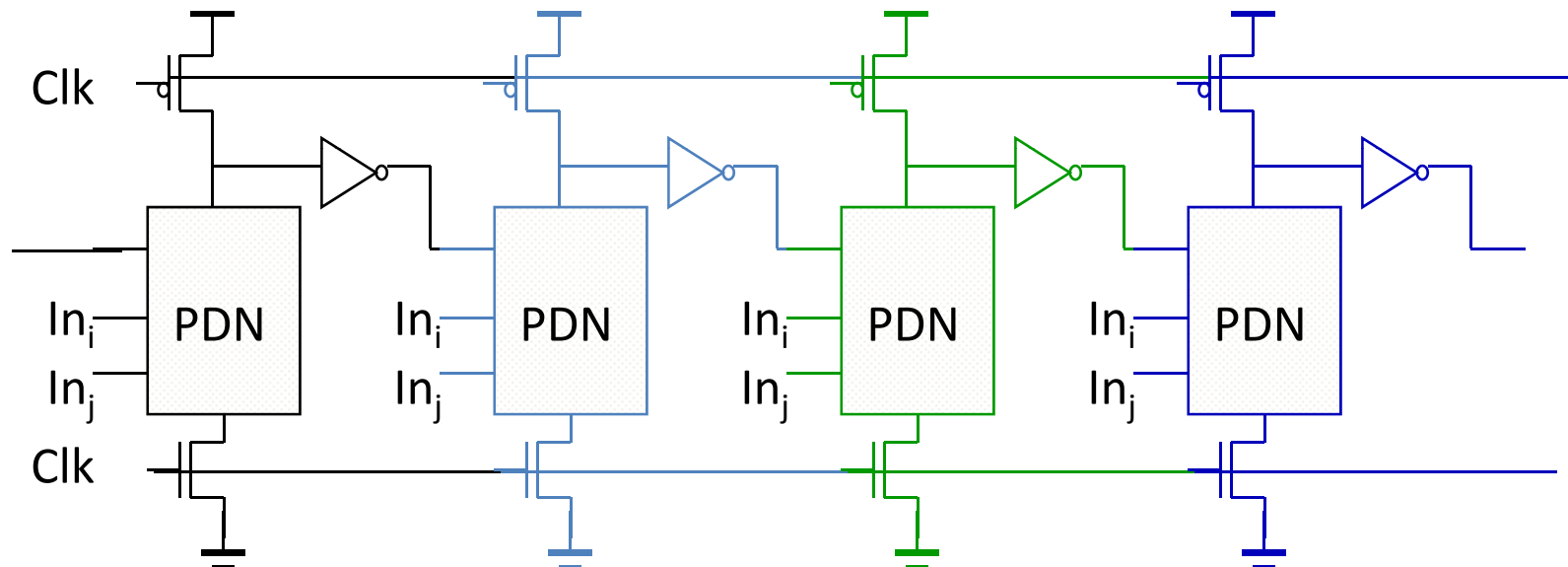
Only 0  $\rightarrow$  1 transitions allowed at inputs!



# Domino Logic



# Why Domino?

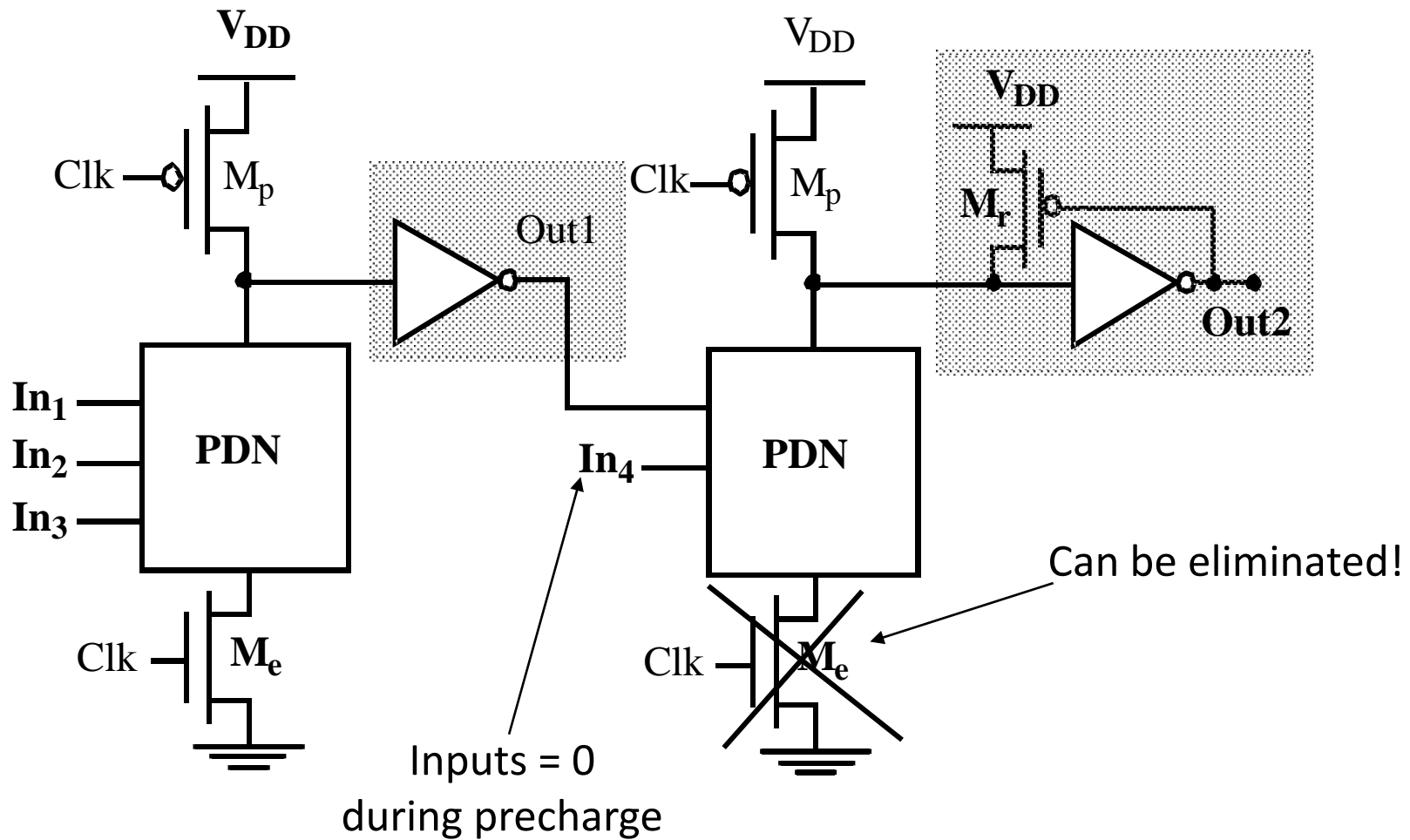


Like falling dominos!

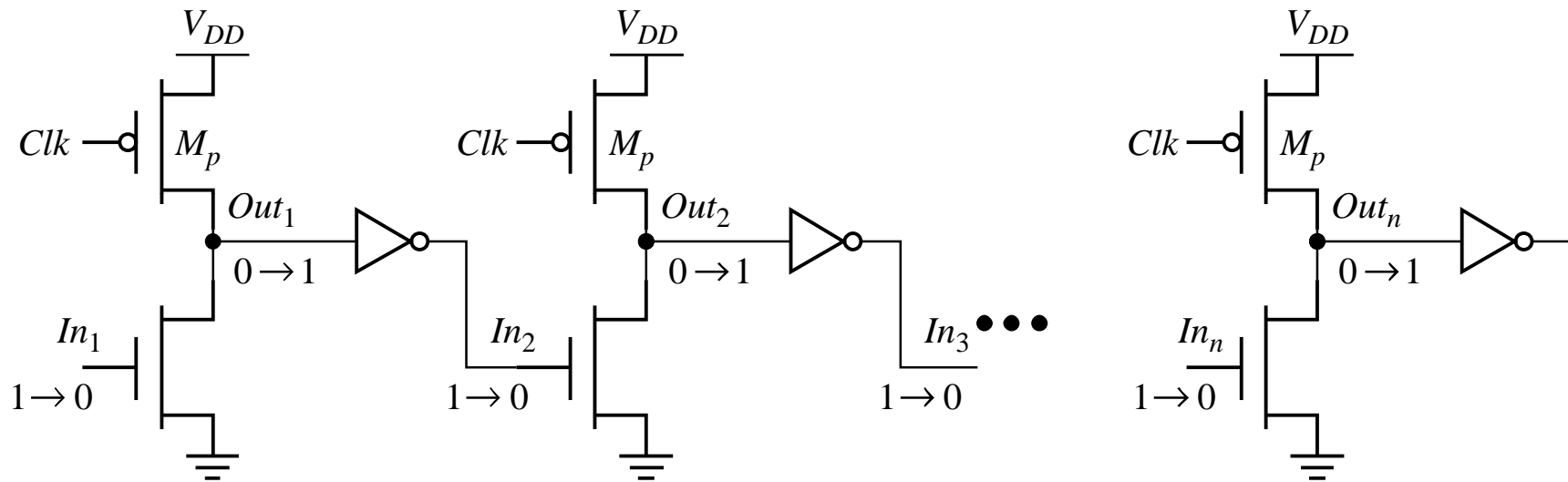
# Properties of Domino Logic

- Only non-inverting logic can be implemented
- Very high speed
  - static inverter can be skewed, only L-H transition
  - Input capacitance reduced – smaller logical effort

# Designing with Domino Logic



# Footless Domino



The first gate in the chain needs a foot switch  
Precharge is rippling – short-circuit current  
A solution is to delay the clock for each stage